

FORM PTO-1595
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U.S. DEPARTMENT OF COMMERCE
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Atty. Docket No. 04284.0788

To the Assistant Commis
Please record the attac.

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/ thereof. ATTN. BOX ASSIGNMENTS

1. Name of conveying party(ies):
Tomoko HONDA
Masaki ADACHI

Additional names(s) of conveying party(ies)
attached? ☐ Yes ☒ No

3. Nature of conveyance:
☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: June 22, 1998

2. Name and address of receiving party(ies):

Name: KABUSHIKI KAISHA TOSHIBA

Internal Address:

Street Address: 72, Horikawa-cho,
Saiwai-ku, Kawasaki-shi, Kanagawa-ken,
Japan

City:

State: ZIP:

Additional name(s) & address(es) attached?
☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application,
the execution date of the application is:

A. Patent Application Nos.

09/092,990

B. Patent No.(s)

Additional numbers attached? ☐ YES ☒ NO

5. Name and address of party to whom
correspondence concerning document
should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address:

Finnegan, Henderson, Farabow, Garrett
& Dunner, L.L.P.

Street Address:

1300 I Street, N.W.

City: Washington, D.C.

State: ZIP: 20005

6. Total number of applications and patents
involved 1

7. Total fee (37 CFR 3.41): \$ 40.00

☒ Enclosed

☐ Authorized to be charged to
deposit account

8. Deposit account number: 06-0916

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct
and any attached copy is a true copy of the original document.

Richard V. Burqujian

Name of Person Signing

Signature

August 28, 1998

Date

Total number of pages including cover sheet, attachments and document: 2

PATENT
REEL: 9417 FRAME: 0689

A S S I G N M E N T

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

THERMOPLASTIC MATERIAL FOR SEALING A SEMICONDUCTOR ELEMENT,
SEMICONDUCTOR DEVICE SEALED BY THE MATERIAL, AND THE PROCESS
FOR MANUFACTURING THE SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters Patent on June 08, 1998, (Serial No. _____); and

WHEREAS, KABUSHIKI KAISHA TOSHIBA, a corporation of Japan, whose post office address is 72, Horikawa-cho, Saiwai-ku, Kawasaki-shi, Kanagawa-ken, Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 09/092,090, filed June 08, 1998) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

1. Full Name of Sole or First Assignor : Assignor's Signature	: Date
<u>Tomoko HONDA</u> : <u>Tomoko Honda</u>	: <u>June 22, 1998</u>
Address c/o Intellectual Property Division Toshiba Corporation	: Citizen of
<u>1-1-1, Shibaura, Minato-ku, Tokyo, Japan</u>	: <u>JAPAN</u>
2. Full Name of Second Assignor : Assignor's Signature	: Date
<u>Masaki ADACHI</u> : <u>Masaki Adachi</u>	: <u>June 22, 1998</u>
Address c/o Intellectual Property Division Toshiba Corporation	: Citizen of
<u>1-1-1, Shibaura, Minato-ku, Tokyo, Japan</u>	: <u>JAPAN</u>
3. Full Name of Third Assignor : Assignor's Signature	: Date
: _____	: _____
Address _____	: Citizen of _____

PATENT